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(12) **United States Design Patent** (10) **Patent No.:** **US D916,039 S**
Yamanaka et al. (45) **Date of Patent:** **** Apr. 13, 2021**

(54) **SEMICONDUCTOR DEVICE**
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(51) **LOC (13) Cl.** **13-03**
(52) **U.S. Cl.**
USPC **D13/182**
(58) **Field of Classification Search**
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CPC H01L 21/00; H01L 21/02; H01L 21/4814; H01L 21/4846; H01L 21/4871; H01L 21/67144; H01L 2224/42; H01L 2224/43; H01L 2224/01; H01L 2224/08055; H01L 2224/08054; H01L 23/12; H01L 23/13; H01L 23/14; H01L 23/147; H01L 23/00; H01L 23/48; H01L 23/4926; H01L 23/495; H01L 23/49517; H01L 23/498; H01L 23/49805; H01L 23/49811; H01L 23/49861; H01L 23/49866; H01L 23/49872; H01L 23/49575; H01L 23/49579; H01L 2924/171; H01L 2924/1711; H01L 2924/1715; H01L 2924/181; H01L 2924/1811; H01L 2924/1815; H01L 2924/19042; H01L 2924/1905

See application file for complete search history.

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(57) **CLAIM**
The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION
FIG. 1 is a front view of a semiconductor device, showing our new design;
FIG. 2 is a rear view thereof;
FIG. 3 is a top view thereof;
FIG. 4 is a bottom view thereof;
FIG. 5 is a left-side view thereof;
FIG. 6 is a right-side view thereof;

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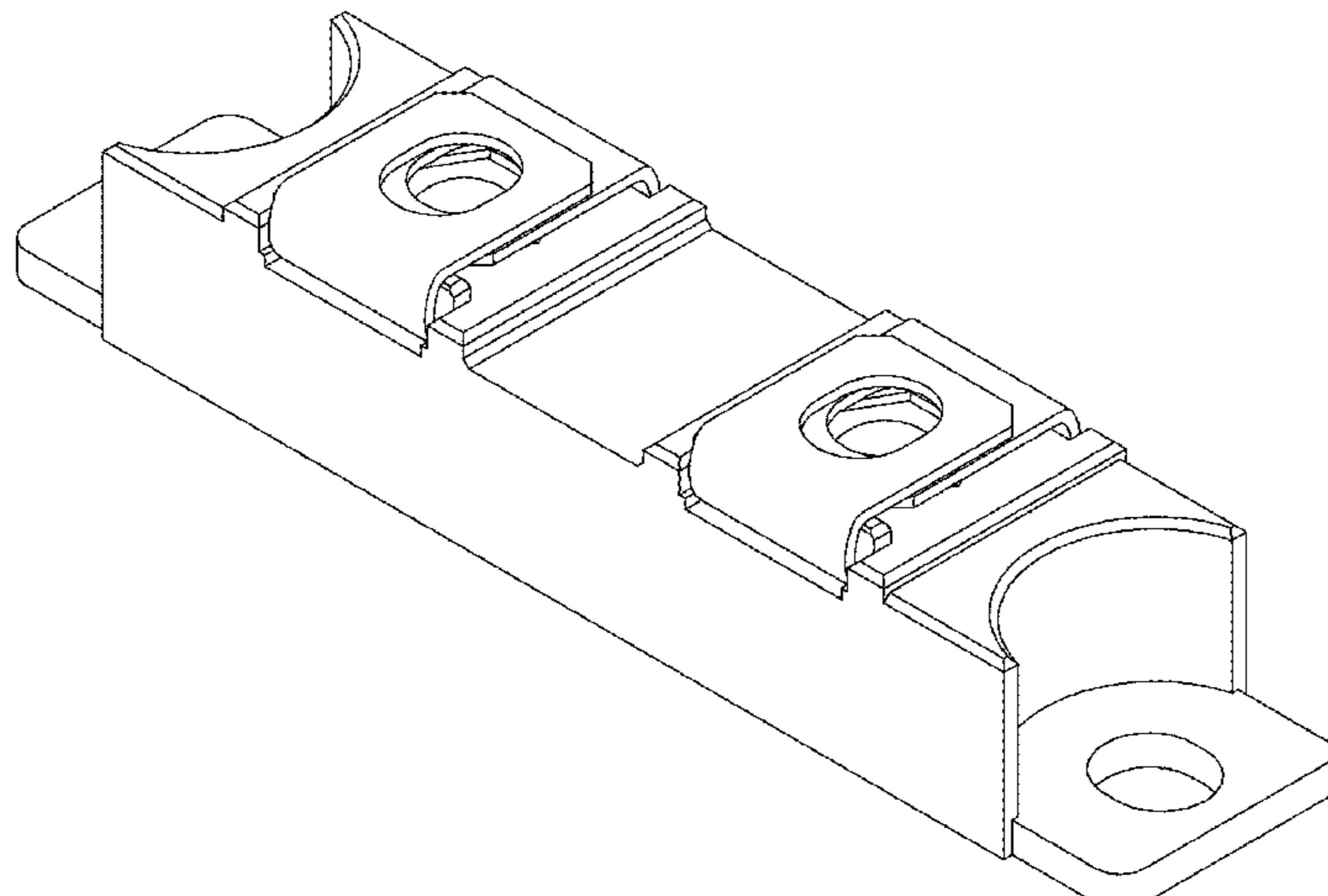


FIG. 7 is a front top perspective view thereof;
FIG. 8 is a rear top perspective view thereof; and,
FIG. 9 is a rear side perspective view thereof.

1 Claim, 9 Drawing Sheets

(56)

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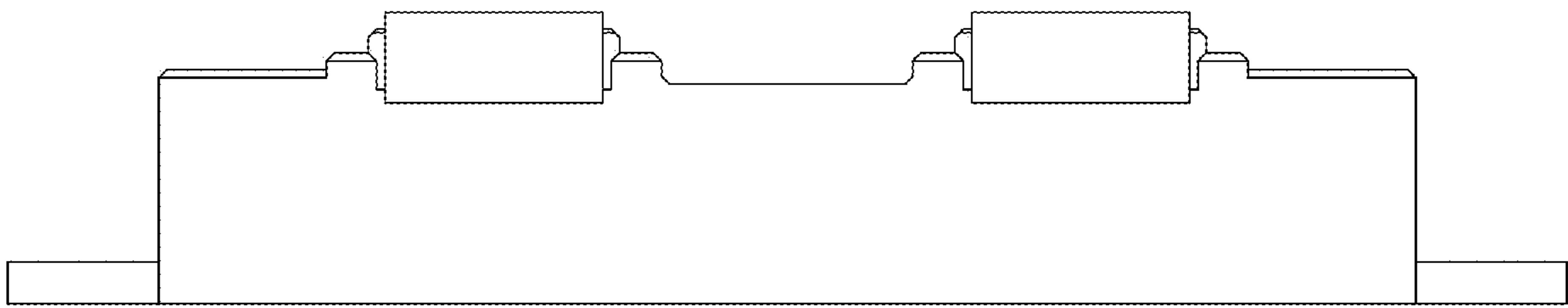


FIG. 1

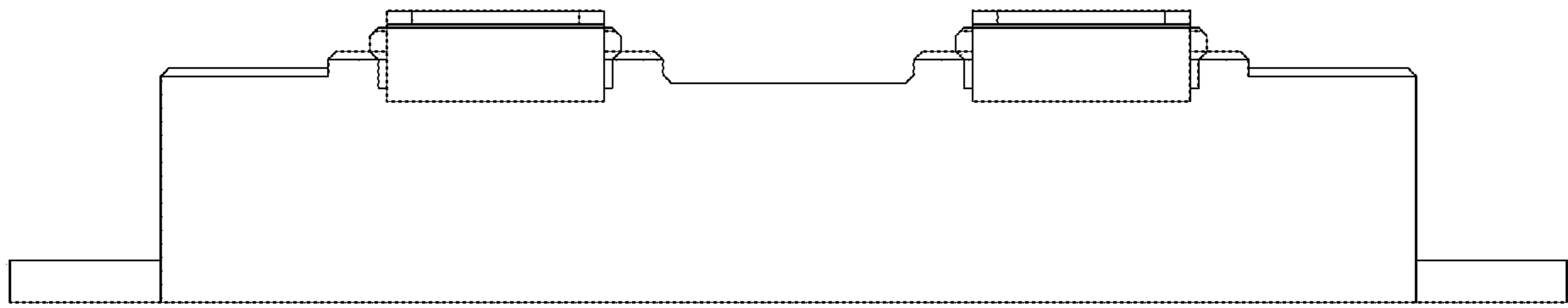


FIG. 2

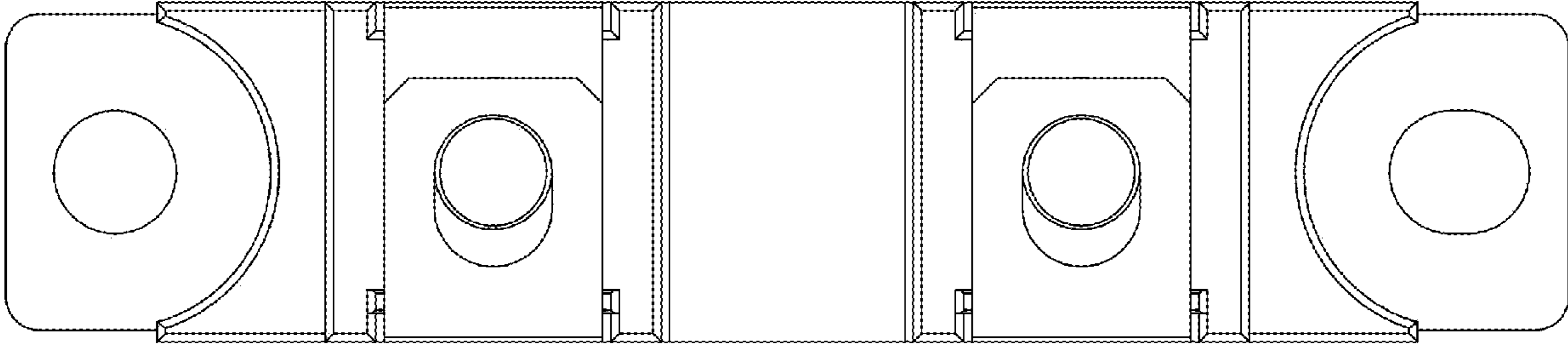


FIG. 3

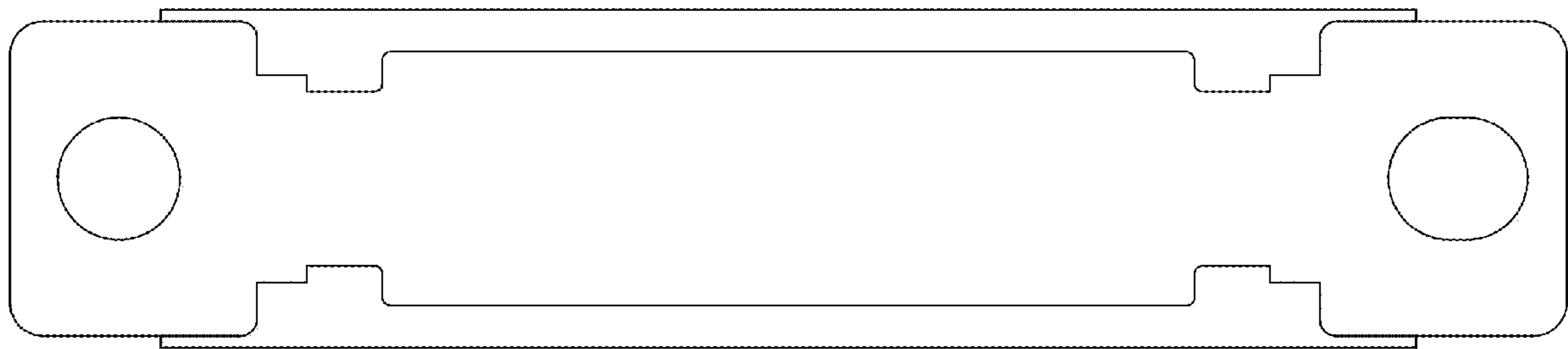


FIG. 4

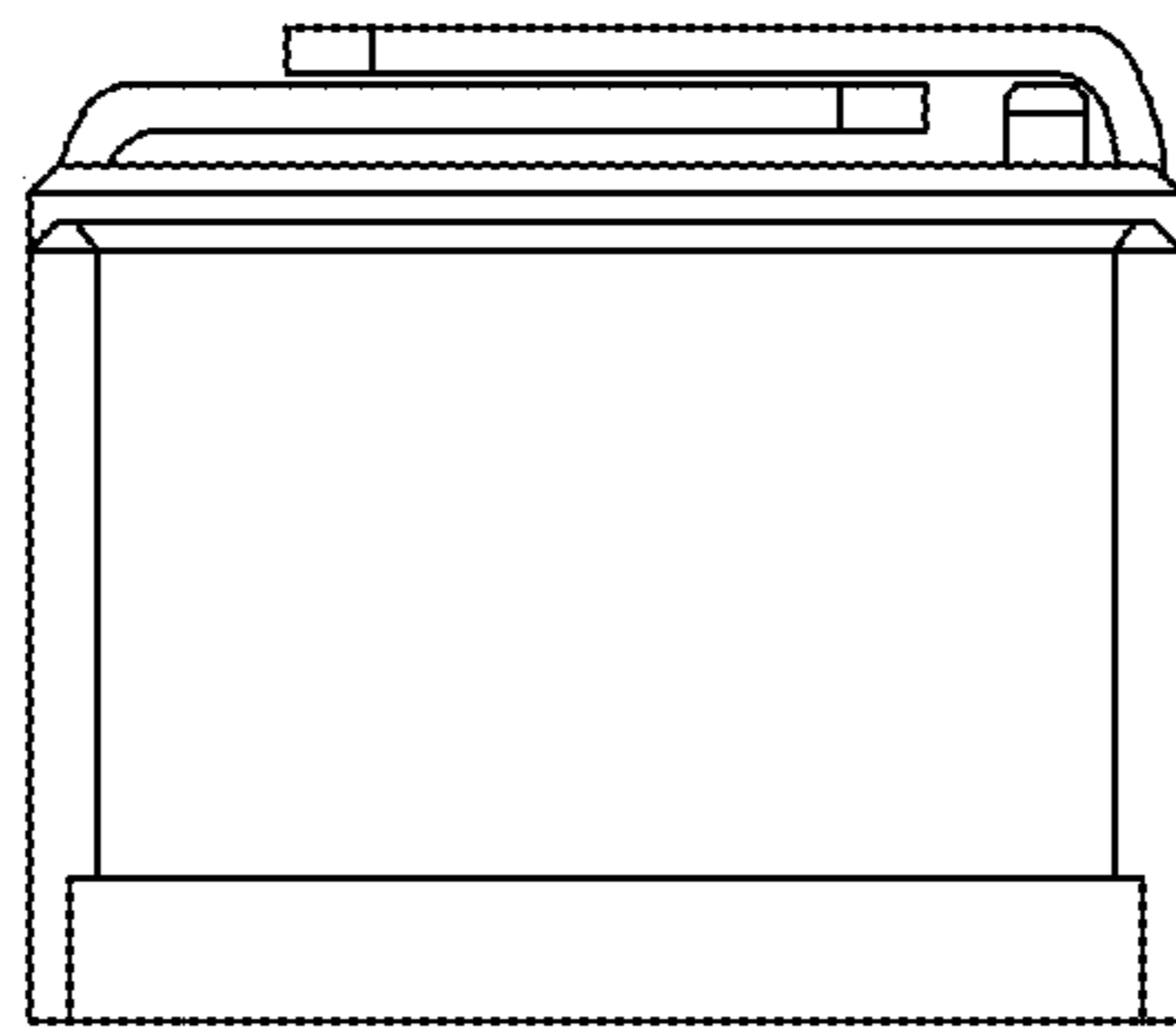


FIG. 5

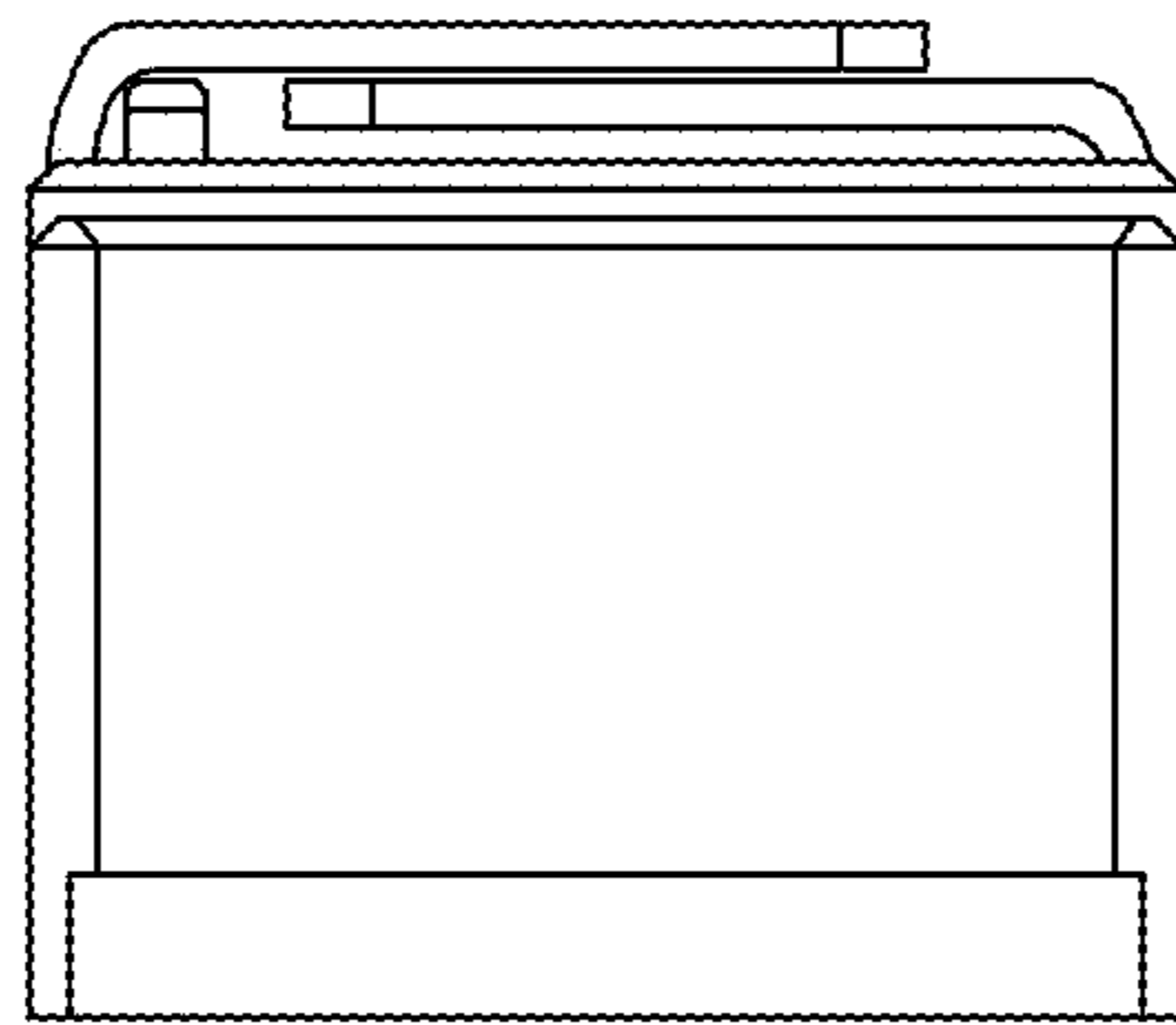


FIG. 6

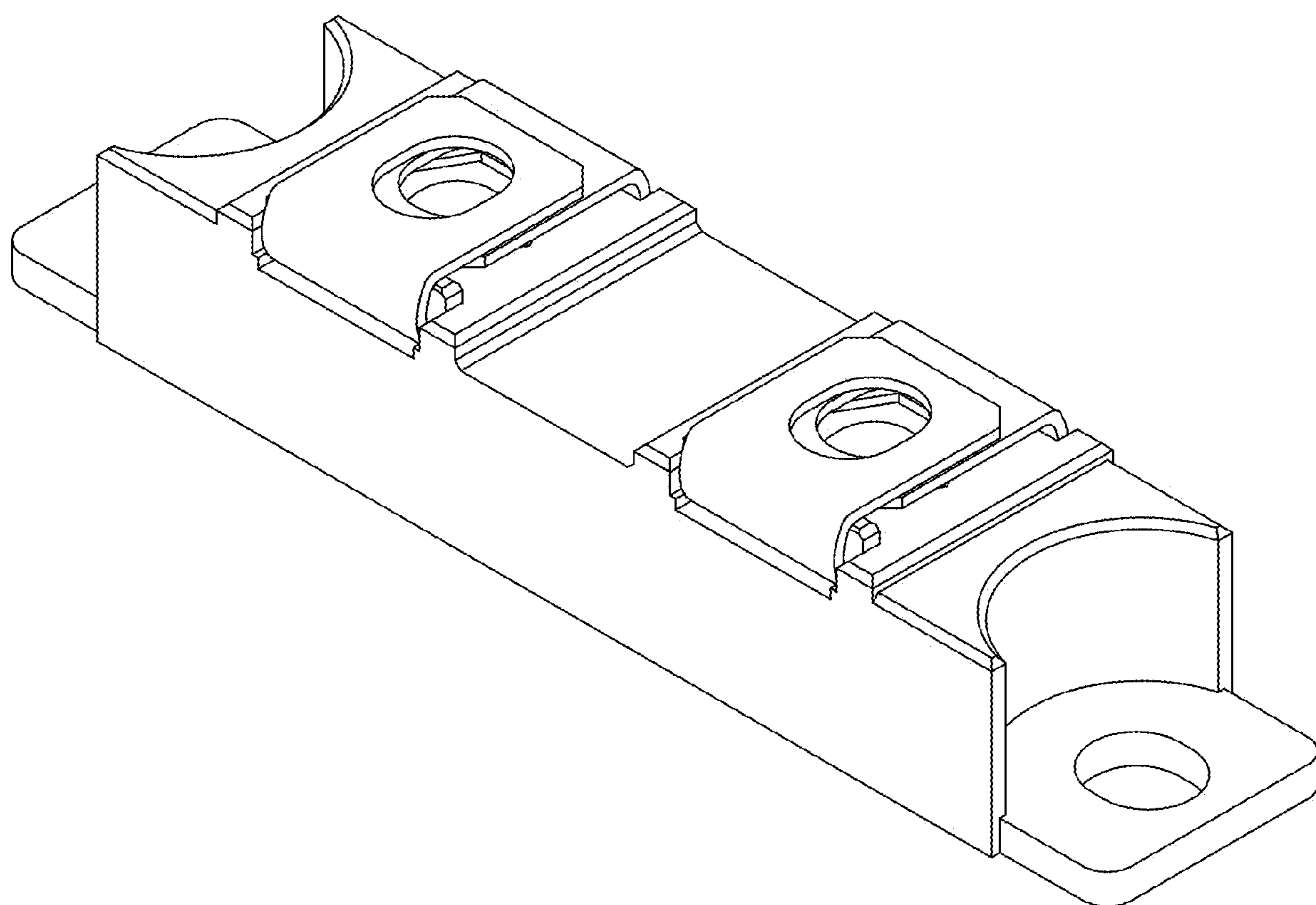


FIG. 7

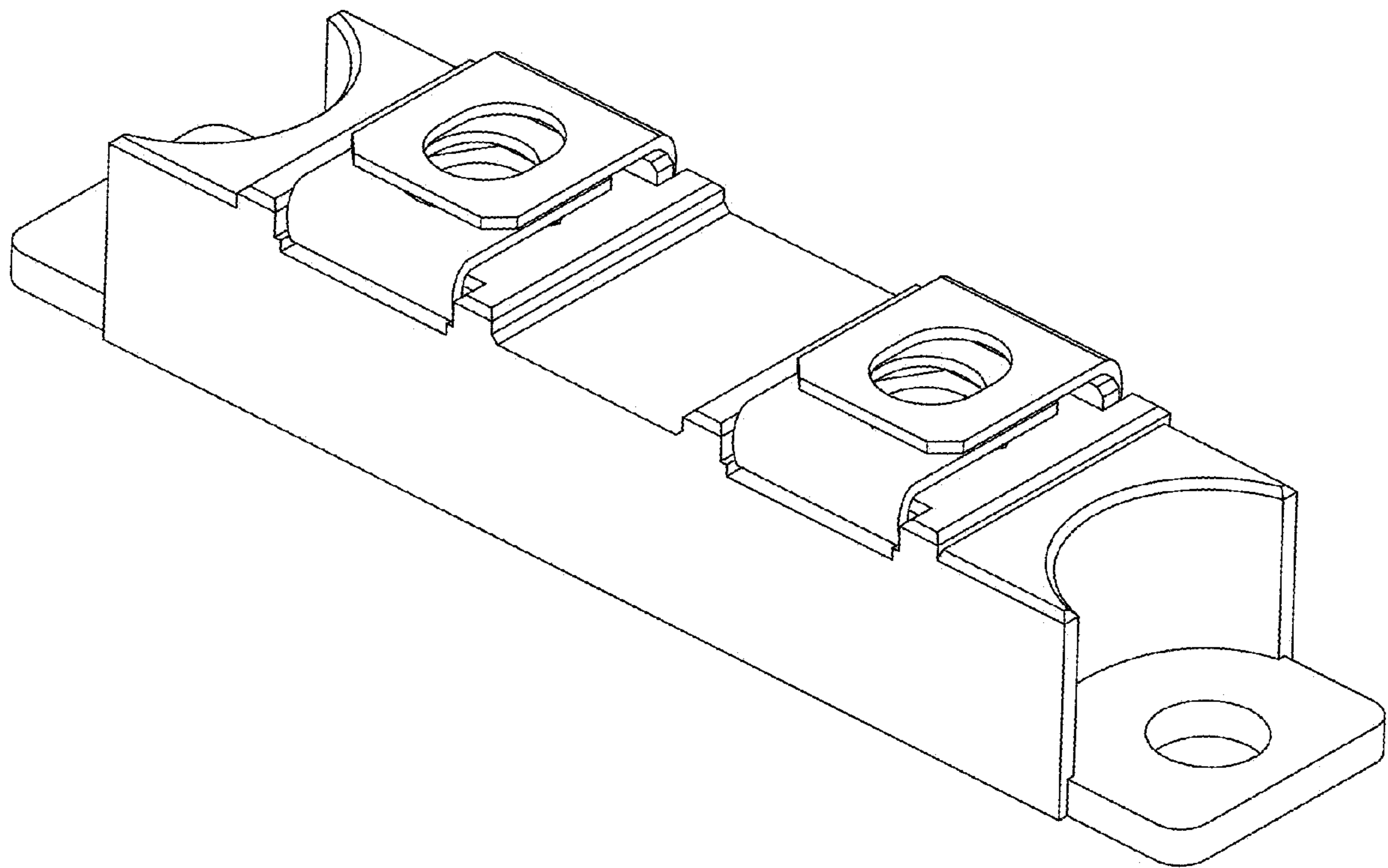


FIG. 8

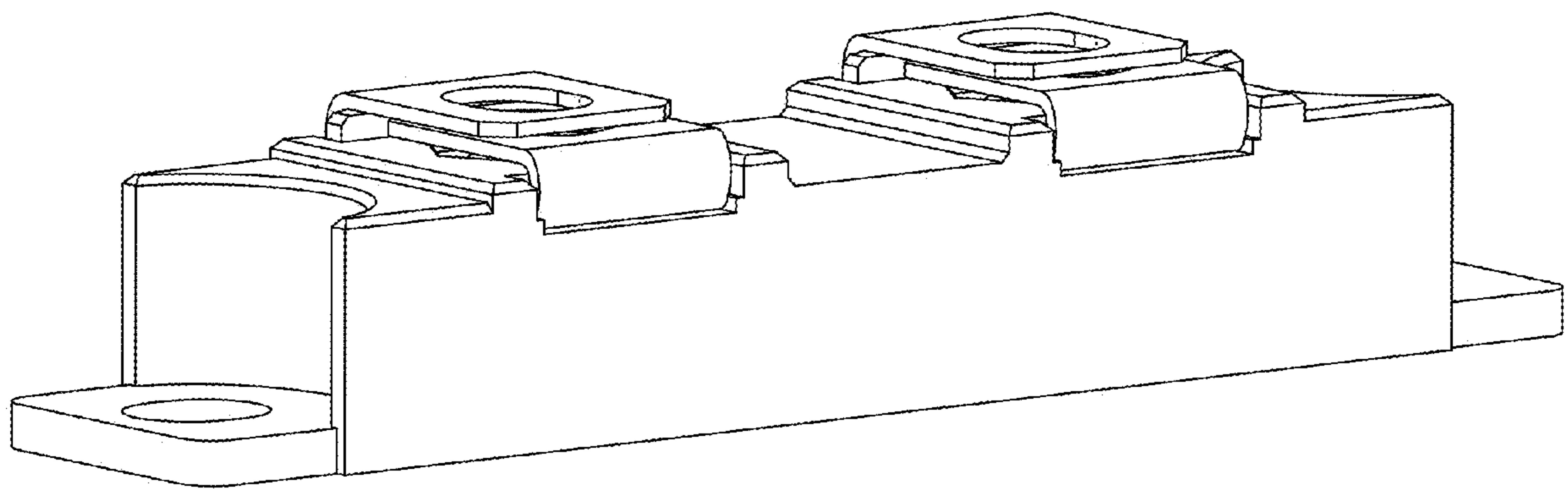


FIG. 9